



iJRASET

International Journal For Research in
Applied Science and Engineering Technology



INTERNATIONAL JOURNAL FOR RESEARCH

IN APPLIED SCIENCE & ENGINEERING TECHNOLOGY

Volume: 10 Issue: V Month of publication: May 2022

DOI: <https://doi.org/10.22214/ijraset.2022.43253>

www.ijraset.com

Call:  08813907089

E-mail ID: ijraset@gmail.com

Simulation of Junctionless Transistor for Low Power Mix Circuit

Yash Mahajan¹, Niraj Morankar², Raj Patil³, Pranjal Patil⁴, Santosh Wagaj⁵

^{1, 2, 3, 4, 5}Dept of Electronics & Telecommunication, JSPM's RSCOE, Tathawade, Pune, MS-India, Savitribai Phule Pune University, Pune

Abstract: In this work simulation of Double Gate Junction less transistor has been carried out. Comparative study of the various parameters namely; transconductance(gm), output conductance(gd), DIBL, Subthreshold slope, Ion/Ioff, electric field and Potential. Simulation is carried out in Cogenda Visual TCAD simulator. Comparative study shows using double gate junctionless transistor reduces short channel effect such as DIBL, Subthreshold Slope, Ion/Ioff. Double Gate Junctionless transistor has higher transconductance(gm) and lower output transconductance(gd) compared to conventional junction transistor.

I. INTRODUCTION

In order to increase the operating speed of circuit, improve the number of transistor on chips and reduce the manufacturing cost of chips, the size of transistors has been reducing over the time[1]. As we reduce the size of the transistor it degrades the performance of transistor due to short channel effect[3]. One of the solution of the issue could be to propose source-channel and Drain-channel junction free transistor called as junctionless transistor(JLT)[2]. Junctionless transistor has uniform doping concentration over source-channel-drain region[5].

In this project Junctionless transistor has double gates to provides better controllability of the gate voltage over drain current[4]. Junctionless and Junction Transistors are simulated in Cogenda Visual TCAD. Various analog parameters are compared between junction and junctionless transistors[6].

II. PROPOSED STRUCTURE

The proposed structure of Double Gate Junctionless Transistor is as shown in Fig.1.

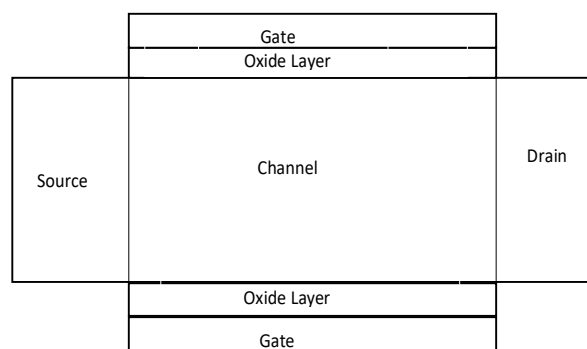


Figure 1 Double Gate Junctionless Transistor

Fig.1 shows the structure of n-channel DGJLT. An n channel DGJLT has a uniform doping of N type material across source, channel and drain. Gate material used is P⁺ polysilicon. Length and Width of Gates is 20nm and 2nm respectively. Thickness of SiO₂ layer is 1nm. Two different metal gates are used in DGJLT. Both the Gate are Interconnected. For DGJLT device, work function of both gate material are set to be 5.1eV Channel thickness of DGJLT is 10nm. Channel doping concentration (N_D) across Source, Channel and Drain is 0.4*10¹⁷ /cm³. Thickness of SiO₂ layer is 1nm.

Table 1: Device parameters

Parameter	DGJLT value	DGJT value
Channel Length	40 nm	40 nm
Channel Width	10 nm	10 nm
Channel doping density	$4 \times 10^{17} / \text{cm}^3$	$1 \times 10^{16} / \text{cm}^3$
Source doping density	-	$1 \times 10^{19} / \text{cm}^3$
Drain doping density	-	$1 \times 10^{19} / \text{cm}^3$
SiO ₂ layer thickness	1 nm	1 nm
Gate m1 affinity	5.1 eV	5.1 eV
Gate m2 affinity	5.1 eV	5.1 eV

III. RESULTS AND DISCUSSION

Simulator Cogenda ‘VisualTCAD’ is used for analyzing device performance in various conditions. Gate work function is kept at 5.1 eV. Transfer characteristic of device for VD of 1V is shown in Fig. 2. Shows Transfer characteristics between ID and VDS for both DGJLT at Gate length from 20nm to 50nm.

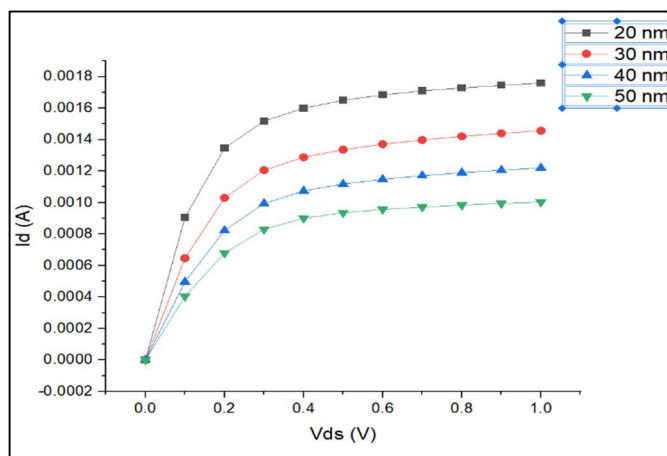


Figure 2 Transfer Characteristics at Vgs= 1 V

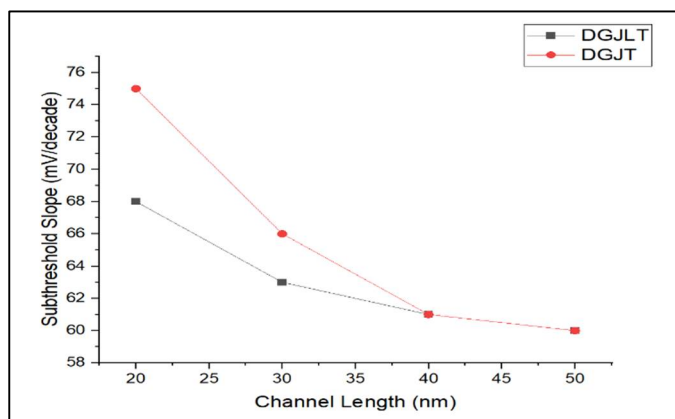


Figure 3 SS for varying main channel length at VDD= 1V.

Figure 3 shows the SS of Junctionless Transistor and Junction Transistor at various channel length. SS is calculated as the slope of I_d versus V_{gs} curve in log scale per decade i.e variation in the gate voltage required to have a decade variation in drain current. SS shows the switching characteristics of the device, lower SS has faster switching. It is observed that Junctionless Transistor has lower SS than Junction Transistor. At Channel Length 50 nm SS limits to its minimum value of 62 mV/decade. This is near to its theoretical limits of 60 mv/decade.

Type	Channel Length (nm)	SS (mV/decade)
DGJT	20	75
	30	66
	40	61
	50	60
DGJLT	20	68
	30	63
	40	61
	50	60

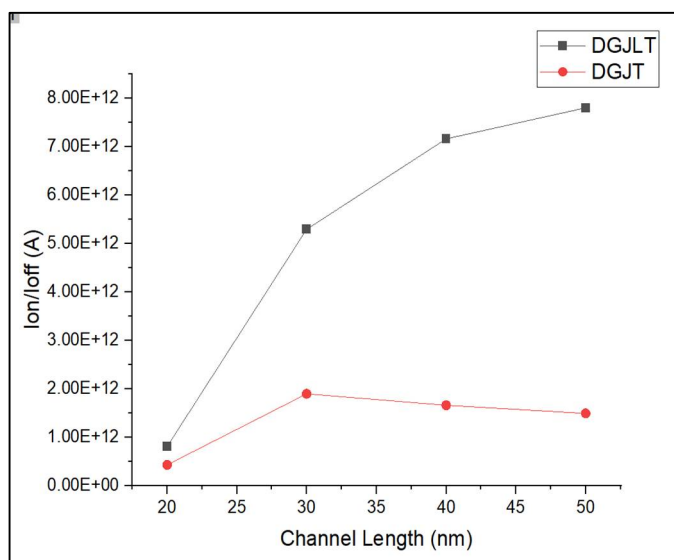


Figure 4 Ion/Ioff at varying channel length at $V_{ds}=1V$

Figure 4 shows the I_{on}/I_{off} of Junctionless Transistor and Junction Transistor at various channel length. To get the value of I_{on} , V_{gs} is kept at 1V and apply 1 V to V_d , whereas to find out I_{off} value of V_{gs} is set to 0 V and V_d is set to 1V. . It is observed that Junctionless Transistor has higher I_{on}/I_{off} ratio than Junction Transistor.

Type	Channel Length (nm)	I_{on}/I_{off} (A)
DGJT	20	4.36E11
	30	2.46E11
	40	1.66E11
	50	1.49E11
DGJLT	20	8.13E11
	30	5.29E12
	40	7.16E12
	50	7.79E12

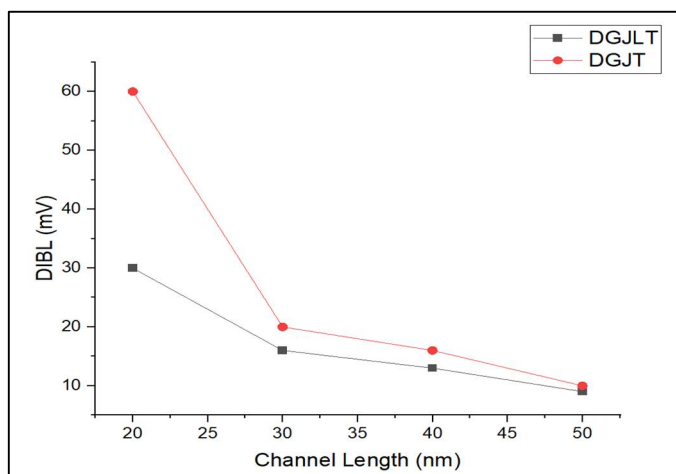


Figure 5 DIBL at varying channel length.

Figure 5 shows the DIBL of the DGJLT and DGJT at with various channel length. DIBL can be calculated as difference in threshold voltage for drain voltage at 50mV and 1V. It is observed that DIBL in case of Junctionless Transistor is lower than Junction Transistor for all channel length. As channel length shrink the DIBL increases. For the Junctionless Transistor value of DIBL is approximately half than Junction Transistor.

Type	Channel Length (nm)	DIBL (mV)
DGJT	20	60
	30	20
	40	16
	50	10
DGJLT	20	30
	30	16
	40	13
	50	9

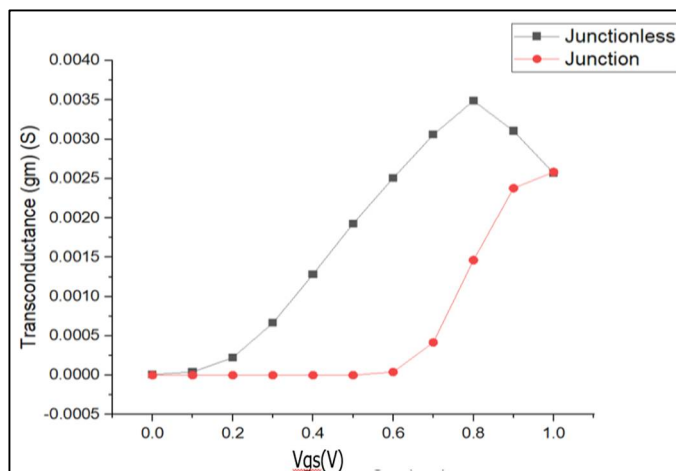


Figure 6 Transconductance at varying Vgs at Lg=20nm

Figure 7 shows the Transconductance(g_m) of proposed Junctionless Transistor and Junction Transistor, at $V_{ds} = 1$ V and Channel length of 20 nm. Transconductance (g_m) is ratio of change in Drain Current(I_d) to the change in Gate Voltage(V_{gs}) at constant Drain to Source voltage(V_{ds}) ($g_m = \delta I_d / \delta V_{gs}$). For better performance of any device Transconductance(g_m) of the device is must high. It can be observed that the Double Gate Junctionless Transistor has higher Transconductance in than Junction Transistor.

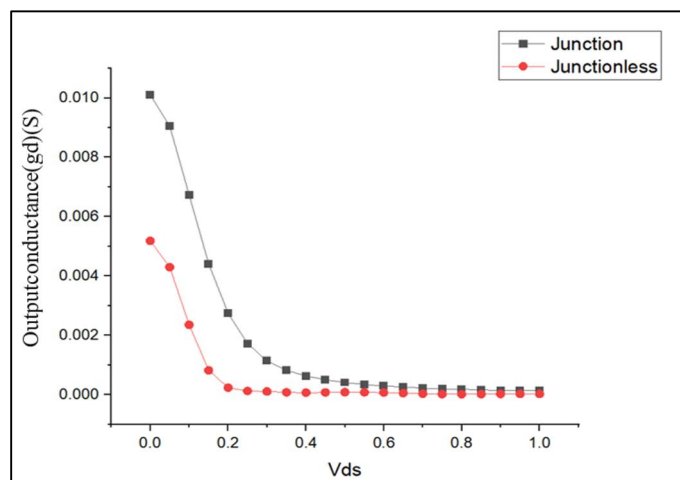


Figure 7 Output conductance at varying V_{ds} at $L_g=20$ nm

Figure 8 shows the Output Conductance(g_d) of Junctionless Transistor and Junction Transistor, at $V_{gs} = 1$ V and $L_g = 20$ nm. Output Conductance(g_d) is ratio of change in Drain Current (I_d) to change in Drain to Source Voltage (V_{ds}) by keeping Gate Voltage(V_{gs}) constant ($g_d = \delta I_d / \delta V_{ds}$). Output Conductance reciprocal of output resistance (R_o). Therefore, for good device performance Output Conductance(g_d) of the device should be low. . It can be observed that the Double Gate Junctionless Transistor has lower Output Conductance in than Junction Transistor.

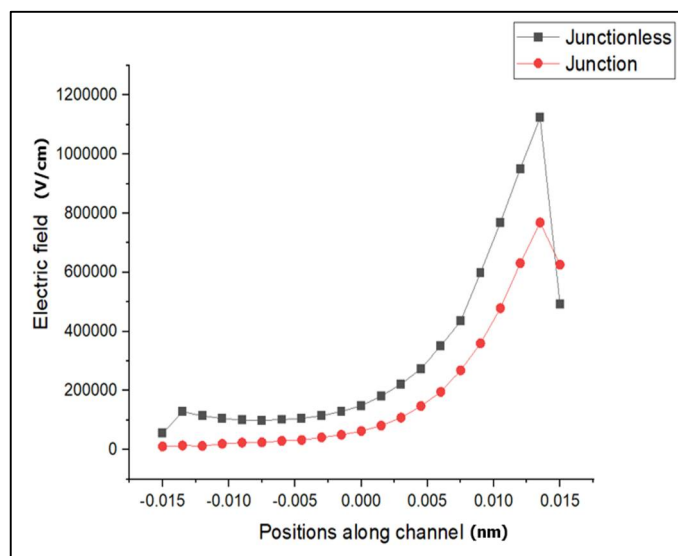


Figure 8 Electric field distribution of DGJLT and DGJT along the channel direction at $V_{GS}=0.5$ V and $V_{DS}=1$ V channel length =30nm

Figure 6 shows the electric field distribution along the channel length at $V_{gs}=0.5$ V and $V_{ds}=1$ V and channel length of 30 nm. It is observed that junctionless transistor has higher electric field compared junction transistor. Both Transistors have higher electric field near drain side of channel.

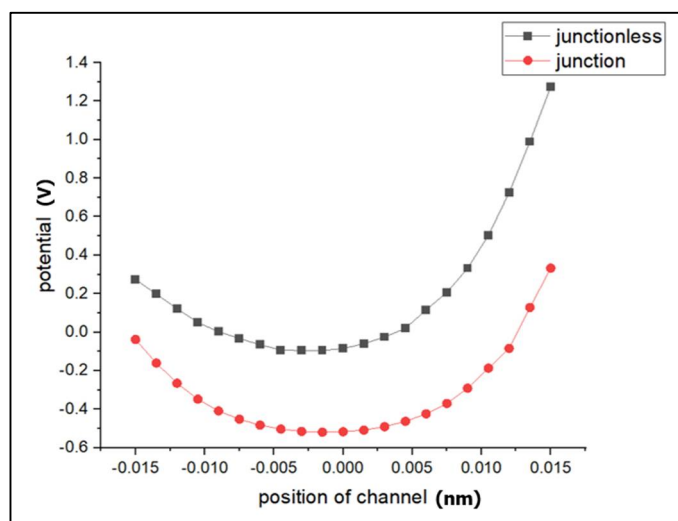


Figure 9 Potential distribution of DGJLT and DGJT along the channel with $V_{DS}=1$ and channel length=30nm.

Figure 9 shows the potential distribution along the channel length. At Drain voltage(V_{ds})=1V and gate voltage(V_{gs}) of 0V to 1V and channel length is 30 nm. It is observed that junctionless transistor has higher potential along the channel compared to junction transistor.

IV. CONCLUSION

All the device parameters are simulated in 2D environment with Cogenda VisualTCAD. It is Observed that when channel length is lesser i.e 20 nm, Junctionless transistor has better results for DIBL (50% improvement). It has better short channel performance in terms of I_{on}/I_{off} ratio and subthreshold slope. Surface potential and Electric Field under channel is improved. Analog Parameters of device is also improved in terms of higher transconductance and lower output conductance. Thus DGJLT is a better device for CMOS technology.

REFERENCES

- [1] G. V. Reddy and M. J. Kumar, "A new dual-material double-gate (DMDG) nanoscale SOI MOSFET-two-dimensional analytical modeling and simulation," in IEEE Transactions on Nanotechnology, vol. 4, no. 2, pp. 260-268, March 2005, doi: 10.1109/TNANO.2004.837845.
- [2] J. Singh, V. Gadi and M. J. Kumar, "Modeling a Dual-Material-Gate Junctionless FET Under Full and Partial Depletion Conditions Using Finite-Differentiation Method," in IEEE Transactions on Electron Devices, vol. 63, no. 6, pp. 2282-2287, June 2016, doi: 10.1109/TED.2016.2555082.
- [3] R. Trevisoli, R. T. Doria, M. de Souza, S. Barraud, M. Vinet and M. A. Pavanello, "Analytical Model for the Dynamic Behavior of Triple-Gate Junctionless Nanowire Transistors," in IEEE Transactions on Electron Devices, vol. 63, no. 2, pp. 856-863, Feb. 2016, doi: 10.1109/TED.2015.2507571.
- [4] J. P. Colinge et al., "SOI gated resistor: CMOS without junctions," 2009 IEEE International SOI Conference, 2009, pp. 1-2, doi: 10.1109/SOI.2009.5318737.
- [5] I. Wong, Y. Chen, S. Huang, W. Tu, Y. Chen and C. W. Liu, "Junctionless Gate-All-Around pFETs Using In-situ Boron-Doped Ge Channel on Si," in IEEE Transactions on Nanotechnology, vol. 14, no. 5, pp. 878-882, Sept. 2015, doi: 10.1109/TNANO.2015.2456182.
- [6] H. Lou et al., "A Junctionless Nanowire Transistor With a Dual-Material Gate," in IEEE Transactions on Electron Devices, vol. 59, no. 7, pp. 1829-1836, July 2012, doi: 10.1109/TED.2012.2192499.



10.22214/IJRASET



45.98



IMPACT FACTOR:
7.129



IMPACT FACTOR:
7.429



INTERNATIONAL JOURNAL FOR RESEARCH

IN APPLIED SCIENCE & ENGINEERING TECHNOLOGY

Call : 08813907089  (24*7 Support on Whatsapp)